

# LNJ052X8ARA

## High Bright Surface Mounting Chip LED

SV (Side View) -0.4 Type

■ Absolute Maximum Ratings  $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	70	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	70	mA
Reverse voltage	$V_R$	5	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

■ Lighting Color

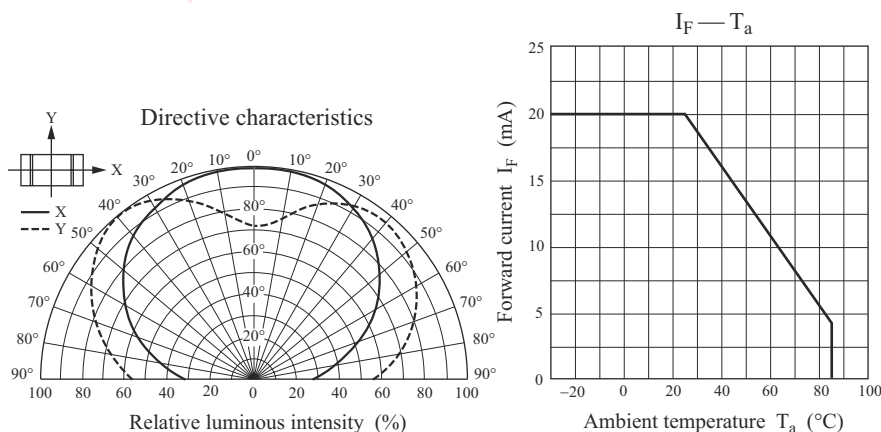
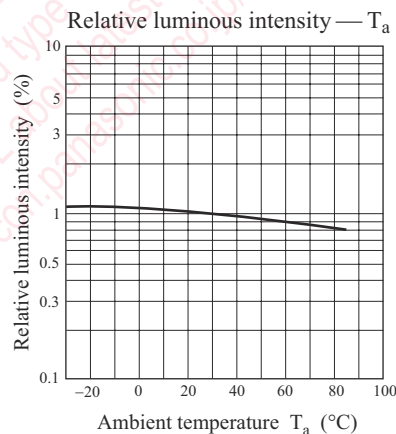
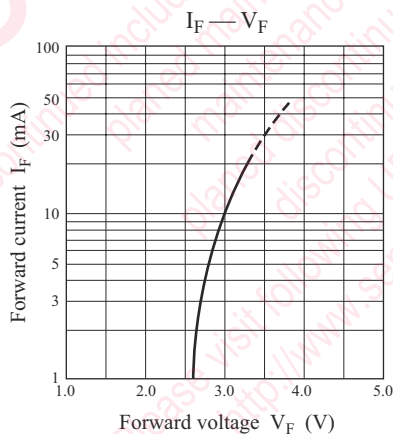
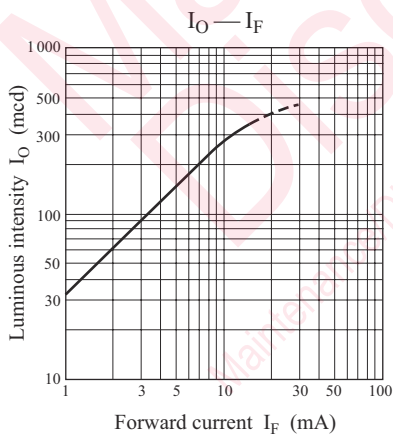
- White

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

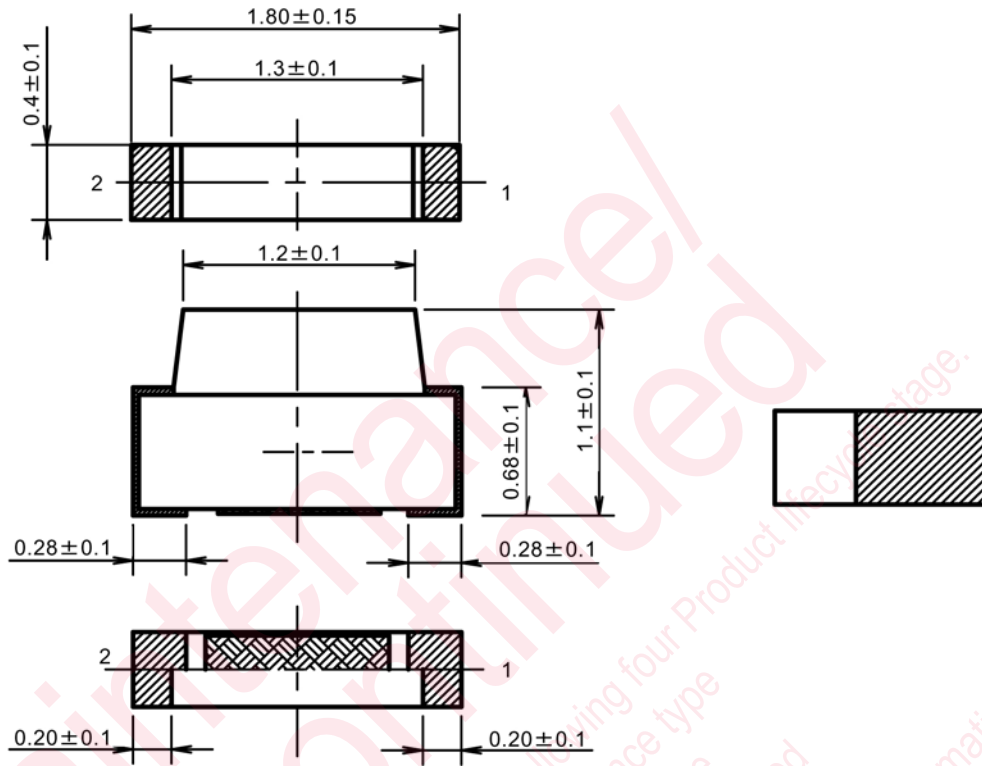
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	$I_O$	$I_F = 10\text{ mA}$	200	280	470	mcd
Reverse current	$I_R$	$V_R = 5\text{ V}$			10	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 10\text{ mA}$	2.7	3.0	3.7	V
Chromaticity coordinates	x	$I_F = 10\text{ mA}$	0.260		0.320	—
	y	$I_F = 10\text{ mA}$	0.208		0.357	—

Note) \*: Measurement tolerance:  $\pm 20\%$



■ Package (Unit: mm)

KLTF5N2K5200



- Pin name
- 1: Anode
- 2: Cathode

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 maintenance type  
 planned discontinued type  
 discontinued type  
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